

## 30 ปี เทคโนโลยีแสง มุ่งสู่อุตสาหกรรมไทย 4.0

Krisda Siangchaew Slider Fabrication Process Development



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### **Slider Fabrication**

Slicing Grinding Lapping Thin film deposition Photolithography Plasma etching Cleaning Testing / inspection











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### Heat-Assisted Magnetic Recording









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### Microanalysis







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## **High Spatial Resolution Performance Measurements**

#### Scanning Thermal Microscopy



 Structural and chemical information are readily available

 Localized, application-specific performance information is lacking and needed

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### **Customized Inspection Metrology and Methodology**



#### R & T spectrometry and data analysis tools





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# LD back heating by head absorption

- Measured laser temperature rises for HAMR3 heads are slightly above the target (<20deg).
- Remarkable head temperature rise due to back-heating – Need to quantify contributions from other heat sources (TFC, Writer).









### **Reflectivity spectrum measurement on ARC coated Rbar**



Microscopic spectrophotometer





ARC reflectivity spectrum estimated from coupon sample measurement

Measured reflectivity spectrum shifts by about 20nm shorter side due to focused beam effect.

## HAMR Light Delivery Design Roadmap

	CY2016				CY2017				CY2018				CY2019			
	CQ1	CQ2	CQ3	CQ4	CQ1	CQ2	CQ3	CQ4	CQ1	CQ2	CQ3	CQ4	CQ1	CQ2	CQ3	CQ4
Product Design Roadmap																
- Slider Platform					uFe	uFemto					uFemto-Long					
- R/W Technology	SMR				TDMR , STAR						TDMR + STAR , HAMR					
- Slider-suspension bond pads	8pads				10pads						12 – 14pads					
HAMR Light Delivery Design	HAMR3/Gen4			Gen5						Gen6						





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## **ARC: Requirements and status**

- Reflectivity spec.: <0.1% averaged over 830+/-30 nm (tentative target)
- Established process control scheme to meet the 
  reflectivity spec. in HICAP.
  - Installed R & T spectrometry and data analysis tools.
  - Established coupon-base process control scheme using reflectivity bottom wavelength.
  - Applied RWN28 with backside pattern.  $\leftarrow$  Verifying.
  - Introducing Rbar-base metrology for direct verification.
- Electrical insulation > 2M  $\Omega$  (between solder pad and slider body)
  - Confirmed >  $10M\Omega$  for ODW ARC. Need to define measuring condition.
  - Need to verify reliability and durability against scratch and other stress.
    - $\rightarrow$  Investigating for the metrology.









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## **Microscopic spectrophotometer**

Objective lens	: Olympus LMPLN-IR 50X $\rightarrow$ Effective multiplication is 27x due to shorter collimator
Fiber	: Irradiation $\phi$ 100um
	: detection $\phi$ 200um + position adjusted
Light source	: HL2000
Collimator	: Edmund f=100mm VIS-NIR
Spectrometer	: Ocean Optics USB2000+ (Measurement range 530~1100nm
	·Reference: Si plate reflection



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840